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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10000229	11/30/2001	257	2.2	2811	

\*\*APPLICANTS: Dias Rajen; Chandran Biju;

\*\*CONTINUING DATA VERIFIED: *HP*

*None*

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\*\* FOREIGN APPLICATIONS VERIFIED: *HP*

*None*

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		42390P12897
Verified and Acknowledged Examiners's initials <i>U.S. / [Signature]</i>		
TITLE : Backside metallization on sides of microelectronic dice for effective thermal contact with heat dissipation devices		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner		
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